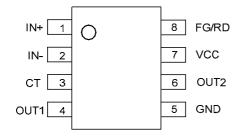


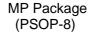
AM4951/R/2

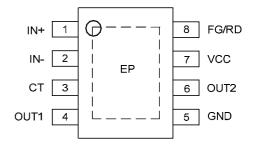
Pin Configuration

MM Package (MSOP-8)



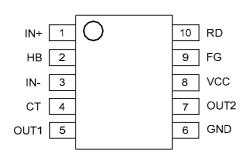






For AM4951/R 24V Application

MM Package (MSOP-10)



For AM4952

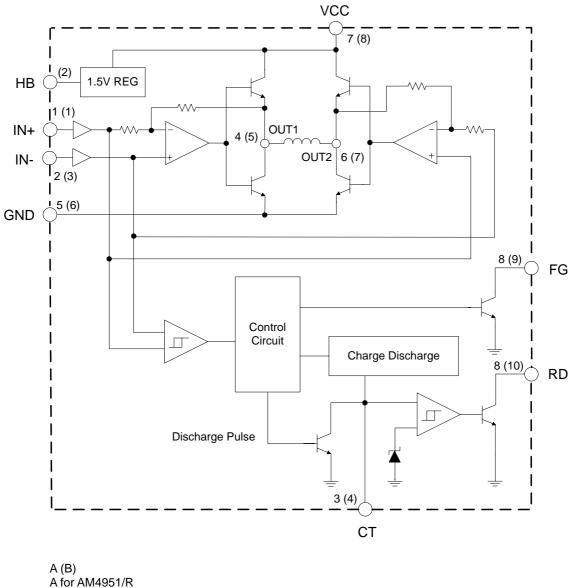
Figure 2. Pin Configuration of AM4951/R/2 (Top View)

Downloaded from Arrow.com.



AM4951/R/2

Functional Block Diagram



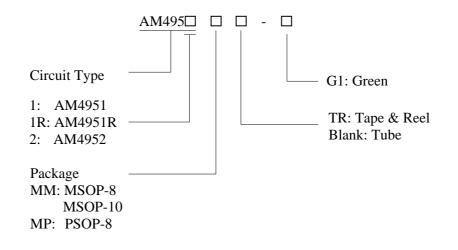
A for AM4951/R B for AM4952

Figure 3. Functional Block Diagram of AM4951/R/2



AM4951/R/2

Ordering Information



Package	Temperature Range	Output Signal	Part Number	Marking ID	Packing Type	
MSOP-8	-40 to 105°C FC	FG	AM4951MM-G1	4951MM-G1	Tube	
			AM4951MMTR-G1	4951MM-G1	Tape & Reel	
		RD	AM4951RMM-G1	4951RMM-G1	Tube	
			AM4951RMMTR-G1	4951RMM-G1	Tape & Reel	
PSOP-8		FG	AM4951MP-G1	4951MP-G1	Tube	
			AM4951MPTR-G1	4951MP-G1	Tape & Reel	
		RD	AM4951RMP-G1	4951RMP-G1	Tube	
			AM4951RMPTR-G1	4951RMP-G1	Tape & Reel	
MSOP-10			AM4952MM-G1	4952MM-G1	Tube	
		FU & KD	AM4952MMTR-G1	4952MM-G1	Tape & Reel	

BCD Semiconductor's Pb-free products, as designated with "G1" suffix in the part number, are RoHS compliant and green.



AM4951/R/2

Absolute Maximum Ratings (Note 1, T_A=25°C)

Parameter	Symbol	Value		Unit	
Supply Voltage	V _{CC}	28		V	
Peak Output Current	I _{OUT}	500		mA	
FG/RD Pull-up Voltage	V _{FG} /V _{RD}	28		V	
FG/RD Output Current	I _{FG} /I _{RD}	10		mA	
		MSOP-8	205		
Thermal Resistance (Junction to Ambient)	θ_{JA}	PSOP-8	110	°C/W	
(Junction to Amolent)		MSOP-10	195		
		MSOP-8	48		
Thermal Resistance (Junction to Case)	θ_{JC}	PSOP-8	36	°C/W	
(Junction to Case)		MSOP-10	46		
	P _D	MSOP-8	585	mW	
Power Dissipation		PSOP-8	960	mW	
		MSOP-10	585	mW	
Operating Temperature	T _{OP}	-40 to 125		°C	
Storage Temperature	T _{STG}	-55 to 150		°C	

Note 1: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Symbol Min		Unit	
Supply Voltage	V _{CC}	2.2	24	V	
Hall Input Voltage	V _{ICM}	0	V _{CC} -1.5	V	
Operating Ambient Temperature	T _A	-40	105	°C	



AM4951/R/2

Electrical Characteristics

 V_{CC} =12V, T_A =25°C, unless otherwise specified.

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Sugaly Current	I _{CC1}	V _{CT} =L	3	6	9	mA
Supply Current	I _{CC2}	V _{CT} =H	2.5	5	7.5	mA
CT Charge Current	I _{CHG}		0.9	1.3	1.5	μΑ
CT Discharge Current	I _{DHG}		0.1	0.15	0.25	μΑ
CT Charge/Discharge Current Ratio	R _{CT}	I _{CHG} / I _{DHG}	6	8	10	
CT Clamp Voltage	V _{CL}		1.3	1.5	1.7	V
CT Comparator Voltage	V _{CP}		0.3	0.5	0.7	V
OUT Low Saturation Voltage	V _{SAT_L}	I _{OUT} =200mA		0.25	0.45	V
OUT High Saturation Voltage	V _{SAT_H}	I _{OUT} =200mA		0.95	1.2	V
Hall Input Sensitivity	V _{HN}			7	15	mV
FG Low Level Voltage (For AM4951/2)	V _{FG}	I _{FG} =5mA		0.15	0.3	V
FG Leakage Current (For AM4951/2)	I _{FGL}	V _{FG} =15V		1	30	μΑ
RD Low Level Voltage (For AM4951R/2)	V _{RD}	I _{RD} =5mA		0.15	0.3	V
RD Leakage Current (For AM4951R/2)	I _{RDL}	V _{RD} =15V		1	30	μΑ
HB Voltage (For AM4952)	V _{HB}	I _{HB} =1mA	1.35	1.5	1.65	V



AM4951/R/2

Typical Performance Characteristics

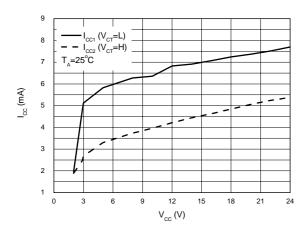


Figure 4. Supply Current vs. Supply Voltage

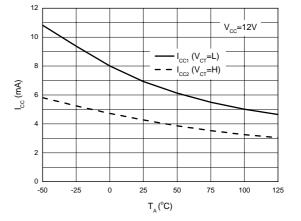


Figure 5. Supply Current vs. Ambient Temperature

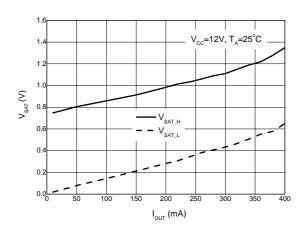


Figure 6. Saturation Voltage vs. Output Current

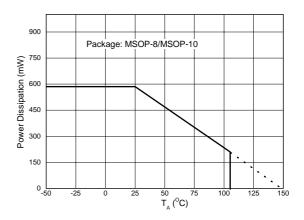


Figure 7. Power Dissipation vs. Ambient Temperature

Downloaded from Arrow.com.



Typical Performance Characteristics (Continued)

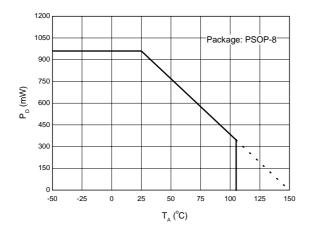
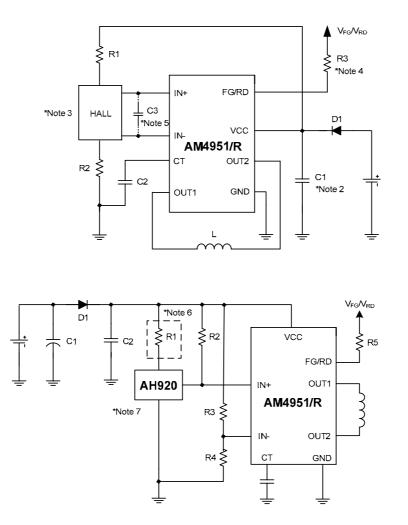


Figure 8. Power Dissipation vs. Ambient Temperature



AM4951/R/2

Typical Application



Note 2: Adding D1 can protect the IC from destruction by reverse connection. If D1 is used, it is necessary to insert a capacitor C1 to provide a regenerative current route. Similarly, if there is no nearby capacitor on the fan power supply line, C1 will also be necessary to improve reliability. Its capacity should be larger than 2.2μ F.

Note 3: If the Hall sensor bias is taken from V_{CC} , A $1/2 V_{CC}$ bias, as shown in the figure must be used. Adjusting the value of R1 and R2 may achieve better startup characteristics and efficiency, even quiet operation.

Note 4: This pin must be left open if unused.

Note 5: If the line between Hall sensor output and Hall sensor input of IC is long, the noise may occur in this line. But it can be eliminated by adding a capacitor C3.

Note 6: Each of R2, R3, R4 and R5 (AM4951/R only) is recommended to be $51k\Omega$ typical. R1 is recommended to be 2k and must be added when V_{CC} is larger than 20V.

Note 7: The package of AH920 is SOT-23-3. If it is packaged in TO-92S-3, please exchange IN- with IN+.

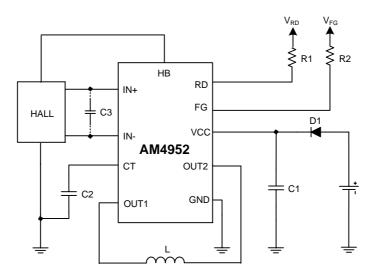
Figure 9. Typical Application of AM4951/R

Apr. 2012 Rev. 1. 4



AM4951/R/2

Typical Application (Continued)



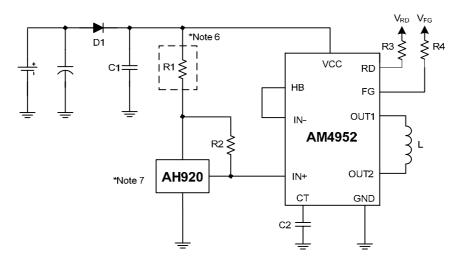


Figure 10. Typical Application of AM4952



Data Sheet

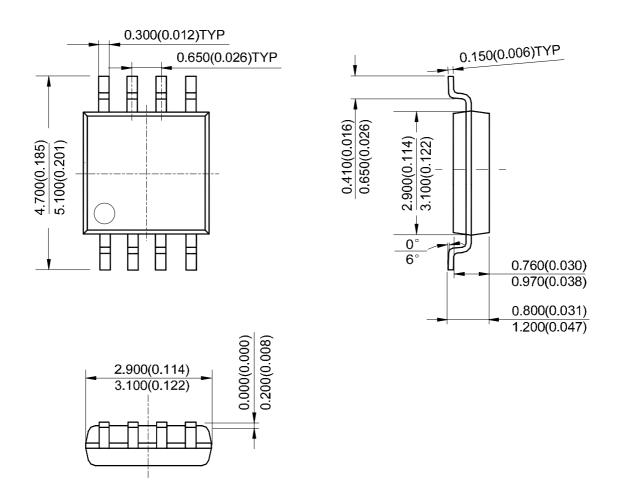
BTL Drive Single-phase Full-wave Fan Motor Driver

AM4951/R/2

Mechanical Dimensions

MSOP-8

Unit: mm(inch)



Note: Eject hole, oriented hole and mold mark is optional.

Apr. 2012 Rev. 1. 4



Data Sheet

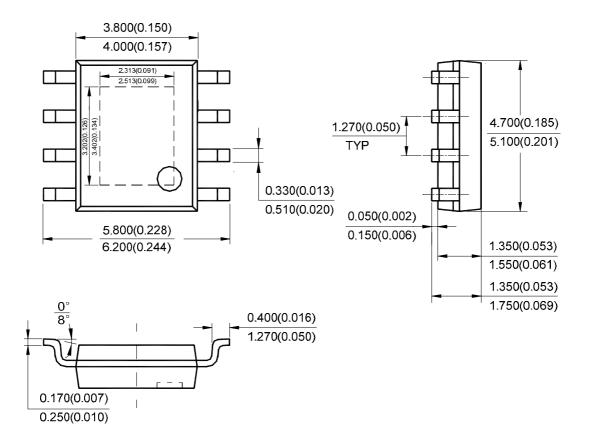
BTL Drive Single-phase Full-wave Fan Motor Driver

AM4951/R/2

Mechanical Dimensions (Continued)

PSOP-8

Unit: mm(inch)



Note: Eject hole, oriented hole and mold mark is optional.



Data Sheet

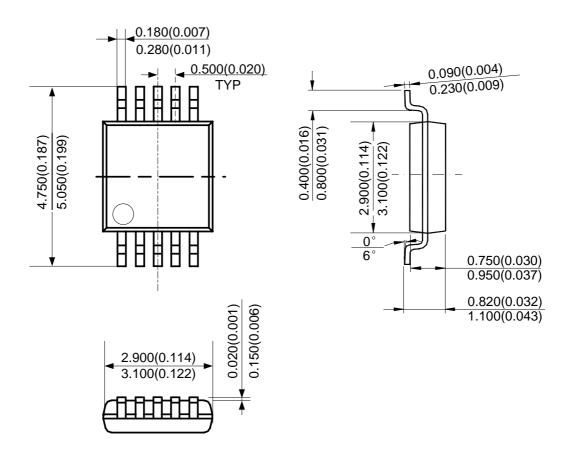
BTL Drive Single-phase Full-wave Fan Motor Driver

AM4951/R/2

Mechanical Dimensions (Continued)

MSOP-10

Unit: mm(inch)



Note: Eject hole, oriented hole and mold mark is optional.

Apr. 2012 Rev. 1. 4



BCD Semiconductor Manufacturing Limited

http://www.bcdsemi.com

IMPORTANT NOTICE

BCD Semiconductor Manufacturing Limited reserves the right to make changes without further notice to any products or specifications herein. BCD Semiconductor Manufacturing Limited does not assume any responsibility for use of any its products for any particular purpose, nor does BCD Semiconductor Manufacturing Limited assume any liability arising out of the application or use of any its products or circuits. BCD Semiconductor Manufacturing Limited does not convey any license under its patent rights or other rights nor the rights of others.

MAIN SITE

- Headquarter

BCD (Shanghai) Micro-electronics Limited No. 1600, Zi Xing Road, Shanghai ZiZhu Science-based Industrial Park, 200241, P. R.C. Tel: +86-021-2416-2266, Fax: +86-021-2416-2277

REGIONAL SALES OFFICE Shenzhen Office

Shanghai SIM-BCD Semiconductor Manufacturing Co., Ltd., Shenzhen Office Unit A Room 1203, Skyworth Bldg., Gaoxin Ave. 1.S., Nanshan District Shenzhen 518057, China Tel: +86-0755-8660-4900 Fax: +86-0755-8660-4958

Taiwan Office (Hsinchu) BCD Semiconductor (Taiwan) Company Limited 8F, No.176, Sec. 2, Gong-Dao 5th Road, East District HsinChu City 300, Taiwan, R.O.C Tel: +886-3-5160181, Fax: +886-3-5160181

- Wafer Fab

Shanghai SIM-BCD Semiconductor Manufacturing Co., Ltd. 800 Yishan Road, Shanghai 200233, China Tel: +021-6485-1491, Fax: +86-021-5450-0008

Taiwan Office (Taipei) BCD Semiconductor (Taiwan) Company Limited 3F, No.17, Lane 171, Sec. 2, Jiu-Zong Rd., Nei-Hu Dist., Taipei(114), Taiwan, R.O.C Tel: +886-2-2656 2808 Fax: +886-2-2656-2806/26562950

USA Office BCD Semiconductor Corp. 48460 Kato Road, Fremont, CA 94538, USA Tel: +1-510-668-1950 Fax: +1-510-668-1990

Korea Office BCD Semiconductor Limited Korea office. Room 101-1112, Digital-Empire II, 486 Sin-dong, Yeongtong-Gu, Suwon-city, Gyeonggi-do, Korea Tel: +82-31-695-8430